

SN54LVT16543, SN74LVT16543 3.3-V ABT 16-BIT REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS148C – MAY 1992 – REVISED JULY 1995

- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low-Static Power Dissipation
- Members of the Texas Instruments *Widebus*™ Family
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Support Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model ($C = 200$ pF, $R = 0$)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Bus-Hold Data Inputs Eliminate the Need for External Pullup Resistors
- Support Live Insertion
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

SN54LVT16543 . . . WD PACKAGE
SN74LVT16543 . . . DGG OR DL PACKAGE
(TOP VIEW)

$\overline{1OEAB}$	1	56	$\overline{1OEBA}$
$\overline{1LEAB}$	2	55	$\overline{1LEBA}$
$\overline{1CEAB}$	3	54	$\overline{1CEBA}$
GND	4	53	GND
1A1	5	52	1B1
1A2	6	51	1B2
V_{CC}	7	50	V_{CC}
1A3	8	49	1B3
1A4	9	48	1B4
1A5	10	47	1B5
GND	11	46	GND
1A6	12	45	1B6
1A7	13	44	1B7
1A8	14	43	1B8
2A1	15	42	2B1
2A2	16	41	2B2
2A3	17	40	2B3
GND	18	39	GND
2A4	19	38	2B4
2A5	20	37	2B5
2A6	21	36	2B6
V_{CC}	22	35	V_{CC}
2A7	23	34	2B7
2A8	24	33	2B8
GND	25	32	GND
$\overline{2CEAB}$	26	31	$\overline{2CEBA}$
$\overline{2LEAB}$	27	30	$\overline{2LEBA}$
$\overline{2OEAB}$	28	29	$\overline{2OEBA}$

description

The 'LVT16543 are 16-bit registered transceivers designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment. These devices can be used as two 8-bit transceivers or one 16-bit transceiver. Separate latch-enable (\overline{LEAB} or \overline{LEBA}) and output-enable (\overline{OEAB} or \overline{OEBA}) inputs are provided for each register to permit independent control in either direction of data flow.

The A-to-B enable (\overline{CEAB}) input must be low in order to enter data from A or to output data from B. If \overline{CEAB} is low and \overline{LEAB} is low, the A-to-B latches are transparent; a subsequent low-to-high transition of \overline{LEAB} puts the A latches in the storage mode. With \overline{CEAB} and \overline{OEAB} both low, the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar but requires using the \overline{CEBA} , \overline{LEBA} , and \overline{OEBA} inputs.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus is a trademark of Texas Instruments Incorporated.

UNLESS OTHERWISE NOTED this document contains PRODUCTION DATA information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265
POST OFFICE BOX 1443 • HOUSTON, TEXAS 77251-1443

Copyright © 1995, Texas Instruments Incorporated

SN54LVT16543, SN74LVT16543

3.3-V ABT 16-BIT REGISTERED TRANSCEIVERS

WITH 3-STATE OUTPUTS

SCBS148C – MAY 1992 – REVISED JULY 1995

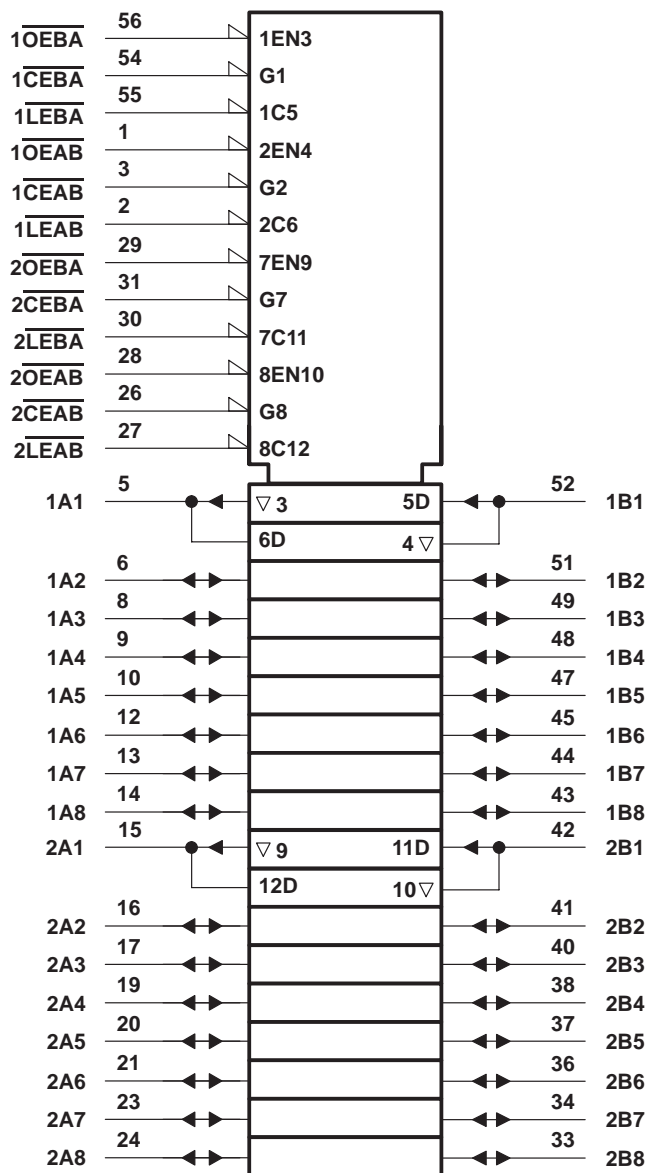
description (continued)

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74LVT16543 is available in TI's shrink small-outline (DL) and thin shrink small-outline (DGG) packages, which provide twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The SN54LVT16543 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74LVT16543 is characterized for operation from -40°C to 85°C .

logic symbol†



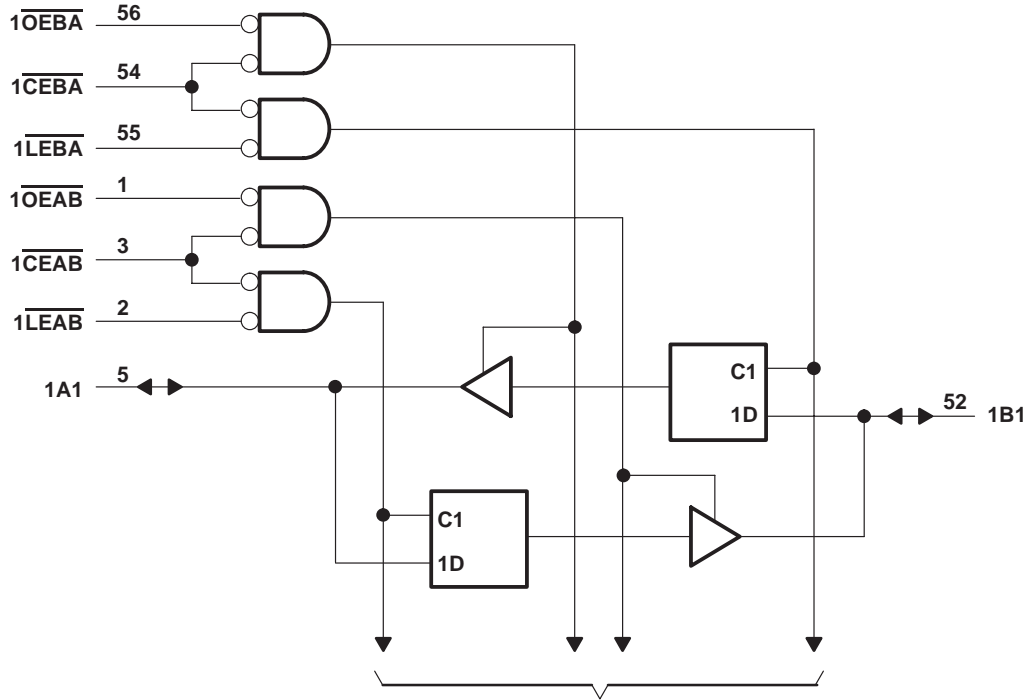
† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



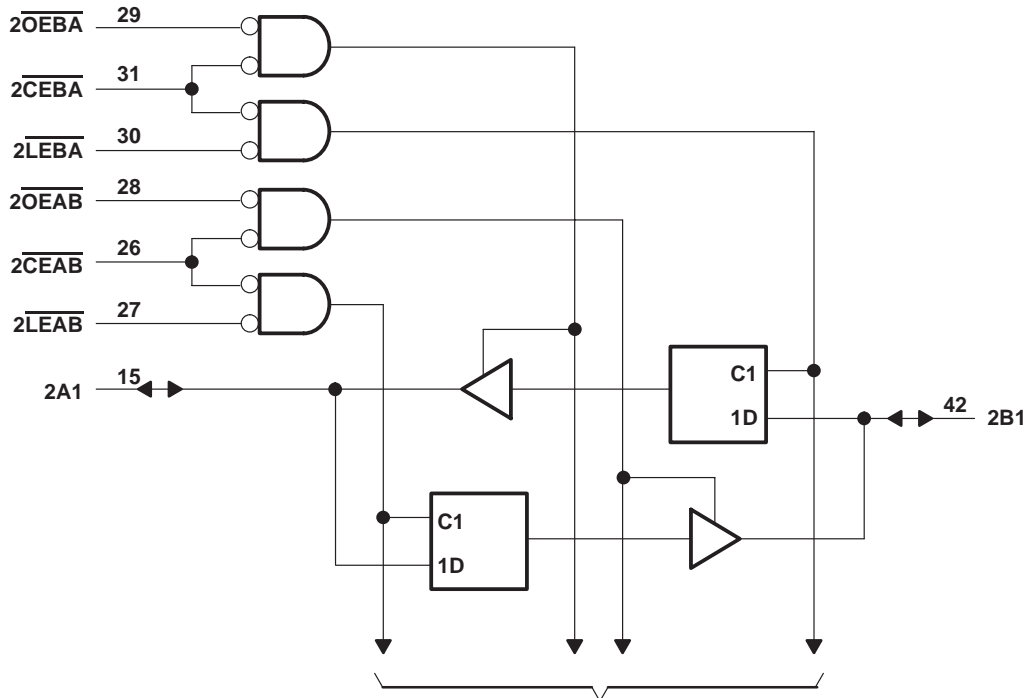
SN54LVT16543, SN74LVT16543
3.3-V ABT 16-BIT REGISTERED TRANSCEIVERS
WITH 3-STATE OUTPUTS

SCBS148C - MAY 1992 - REVISED JULY 1995

logic diagram (positive logic)



To Seven Other Channels



To Seven Other Channels



SN54LVT16543, SN74LVT16543

3.3-V ABT 16-BIT REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS148C – MAY 1992 – REVISED JULY 1995

FUNCTION TABLE†
(each 8-bit section)

INPUTS				OUTPUT B
CEAB	LEAB	OEAB	A	
H	X	X	X	Z
X	X	H	X	Z
L	H	L	X	B ₀ ‡
L	L	L	L	L
L	L	L	H	H

† A-to-B data flow is shown; B-to-A flow control is the same except that it uses \overline{CEBA} , \overline{LEBA} , and \overline{OEBA} .

‡ Output level before the indicated steady-state input conditions were established

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)§

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, V_O (see Note 1)	–0.5 V to 7 V
Current into any output in the low state, I_{OL} : SN54LVT16543	96 mA
SN74LVT16543	128 mA
Current into any output in the high state, I_{OH} (see Note 2): SN54LVT16543	48 mA
SN74LVT16543	64 mA
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 3): DGG package	1 W
DL package	1.4 W
Storage temperature range, T_{stg}	–65°C to 150°C

§ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
 3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 4)

		SN54LVT16543		SN74LVT16543		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	2.7	3.6	2.7	3.6	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage		5.5		5.5	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled			10	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265
POST OFFICE BOX 1443 • HOUSTON, TEXAS 77251-1443

SN54LVT16543, SN74LVT16543
3.3-V ABT 16-BIT REGISTERED TRANSCEIVERS
WITH 3-STATE OUTPUTS

SCBS148C – MAY 1992 – REVISED JULY 1995

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54LVT16543		SN74LVT16543		UNIT
			MIN	TYP†	MAX	MIN	
V_{IK}	$V_{CC} = 2.7\text{ V}$, $I_I = -18\text{ mA}$		-1.2		-1.2		V
V_{OH}	$V_{CC} = \text{MIN to MAX}^\ddagger$, $I_{OH} = -100\ \mu\text{A}$		$V_{CC} - 0.2$		$V_{CC} - 0.2$		V
	$V_{CC} = 2.7\text{ V}$, $I_{OH} = -8\text{ mA}$		2.4		2.4		
	$V_{CC} = 3\text{ V}$	$I_{OH} = -24\text{ mA}$	2		2		
$I_{OH} = -32\text{ mA}$							
V_{OL}	$V_{CC} = 2.7\text{ V}$	$I_{OL} = 100\ \mu\text{A}$	0.2		0.2		V
		$I_{OL} = 24\text{ mA}$	0.5		0.5		
	$V_{CC} = 3\text{ V}$	$I_{OL} = 16\text{ mA}$	0.4		0.4		
		$I_{OL} = 32\text{ mA}$	0.5		0.5		
		$I_{OL} = 48\text{ mA}$	0.55		0.55		
		$I_{OL} = 64\text{ mA}$					
I_I	$V_{CC} = 3.6\text{ V}$, $V_I = V_{CC}$ or GND		Control inputs		± 1		μA
	$V_{CC} = 0$ or MAX^\ddagger , $V_I = 5.5\text{ V}$				10		
	$V_{CC} = 3.6\text{ V}$	$V_I = 5.5\text{ V}$	A or B ports §		20		
		$V_I = V_{CC}$			5		
		$V_I = 0$			-10		
I_{off}	$V_{CC} = 0$, V_I or $V_O = 0$ to 4.5 V				± 100		μA
$I_{I(\text{hold})}$	$V_{CC} = 3\text{ V}$	$V_I = 0.8\text{ V}$	A or B ports		75		μA
		$V_I = 2\text{ V}$			-75		
I_{OZH}	$V_{CC} = 3.6\text{ V}$, $V_O = 3\text{ V}$			1		μA	
I_{OZL}	$V_{CC} = 3.6\text{ V}$, $V_O = 0.5\text{ V}$			-1		μA	
I_{CC}	$V_{CC} = 3.6\text{ V}$, $V_I = V_{CC}$ or GND	$I_O = 0$,	Outputs high		0.12		mA
			Outputs low		5		
			Outputs disabled		0.12		
ΔI_{CC}^\parallel	$V_{CC} = 3\text{ V to }3.6\text{ V}$, One input at $V_{CC} - 0.6\text{ V}$, Other inputs at V_{CC} or GND		0.2		0.2		mA
C_i	$V_I = 3\text{ V or }0$		4		4		pF
C_{iO}	$V_O = 3\text{ V or }0$		13		13		pF

† All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

§ Unused pins at V_{CC} or GND

¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



SN54LVT16543, SN74LVT16543

3.3-V ABT 16-BIT REGISTERED TRANSCEIVERS

WITH 3-STATE OUTPUTS

SCBS148C – MAY 1992 – REVISED JULY 1995

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			SN54LVT16543				SN74LVT16543				UNIT
			$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		$V_{CC} = 2.7\text{ V}$		
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_{w}	Pulse duration, \overline{LEAB} or \overline{LEBA} low		3.3		3.3		3.3		3.3	ns	
t_{su}	Setup time	A or B before $\overline{LEAB}\uparrow$ or $\overline{LEBA}\uparrow$	Data high	0.8	0.5		0.8	0.5		ns	
			Data low	1.5	1.9		1.5	1.9			
	A or B before $\overline{CEAB}\uparrow$ or $\overline{CEBA}\uparrow$	Data high	0.7	0.4		0.7	0.4		ns		
		Data low	1.6	1.9		1.6	1.9				
t_h	Hold time	A or B after $\overline{LEAB}\uparrow$ or $\overline{LEBA}\uparrow$	Data high	0.8	0		0.8	0		ns	
			Data low	1.2	1.3		1.2	1.3			
	A or B after $\overline{CEAB}\uparrow$ or $\overline{CEBA}\uparrow$	Data high	0.8	0		0.8	0		ns		
		Data low	1.3	1.4		1.3	1.4				

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54LVT16543				SN74LVT16543				UNIT	
			$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$			$V_{CC} = 2.7\text{ V}$		
			MIN	MAX	MIN	MAX	MIN	TYP†	MAX	MIN		MAX
t_{PLH}	A or B	B or A	1.4	5		5.8	1.4	2.7	4.6		5.5	ns
t_{PHL}			1.3	4.7		5.9	1.3	2.9	4.6		5.8	
t_{PLH}	\overline{LE}	A or B	1.3	6.8		8.5	1.7	3.7	6.3		8.1	ns
t_{PHL}			1.5	6.5		8.3	1.9	3.7	6		7.8	
t_{PZH}	\overline{OE}	A or B	1.4	6		7.7	1.5	3.3	5.8		7.6	ns
t_{PZL}			1.6	6.3		8.4	1.6	3.3	6.2		8.2	
t_{PHZ}	\overline{OE}	A or B	2	6.7		7.3	2	4.1	6.5		7.1	ns
t_{PLZ}			2.7	6		6.2	2.7	3.9	5.8		5.9	
t_{PZH}	\overline{CE}	A or B	1.4	6.2		7.7	1.5	3.3	6		7.6	ns
t_{PZL}			1.6	6.6		8.5	1.7	3.3	6.4		8.3	
t_{PHZ}	\overline{CE}	A or B	2	6.6		7.2	2	4.1	6.4		7.1	ns
t_{PLZ}			2.6	5.6		5.9	2.6	4	5.4		5.6	

† All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

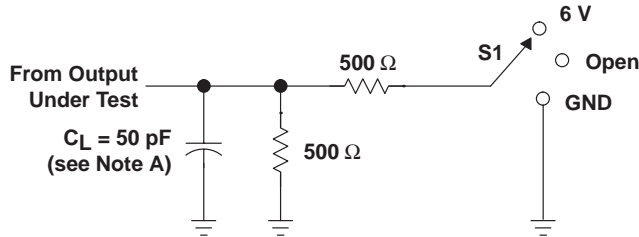
PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



SN54LVT16543, SN74LVT16543 3.3-V ABT 16-BIT REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS

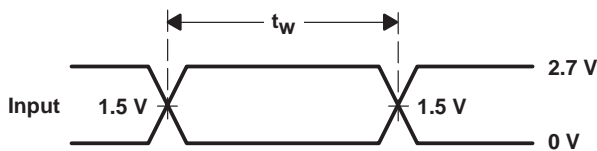
SCBS148C – MAY 1992 – REVISED JULY 1995

PARAMETER MEASUREMENT INFORMATION

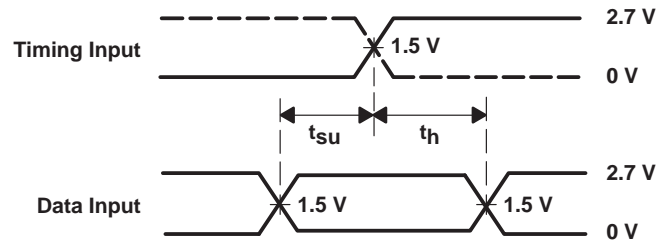


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND

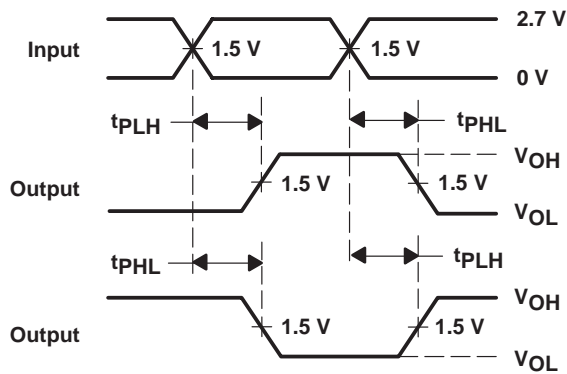
LOAD CIRCUIT FOR OUTPUTS



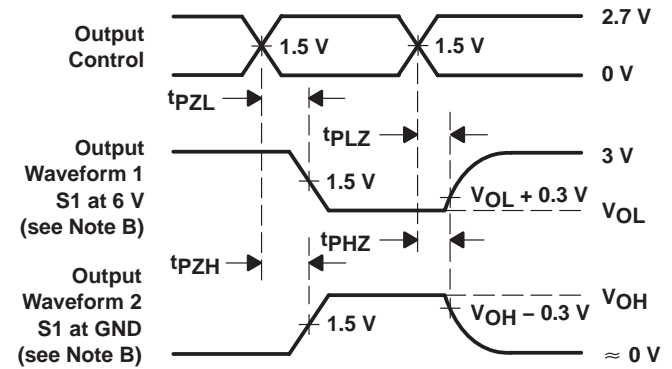
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVT16543DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
SN74LVT16543DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

TAPE AND REEL BOX DIMENSIONS

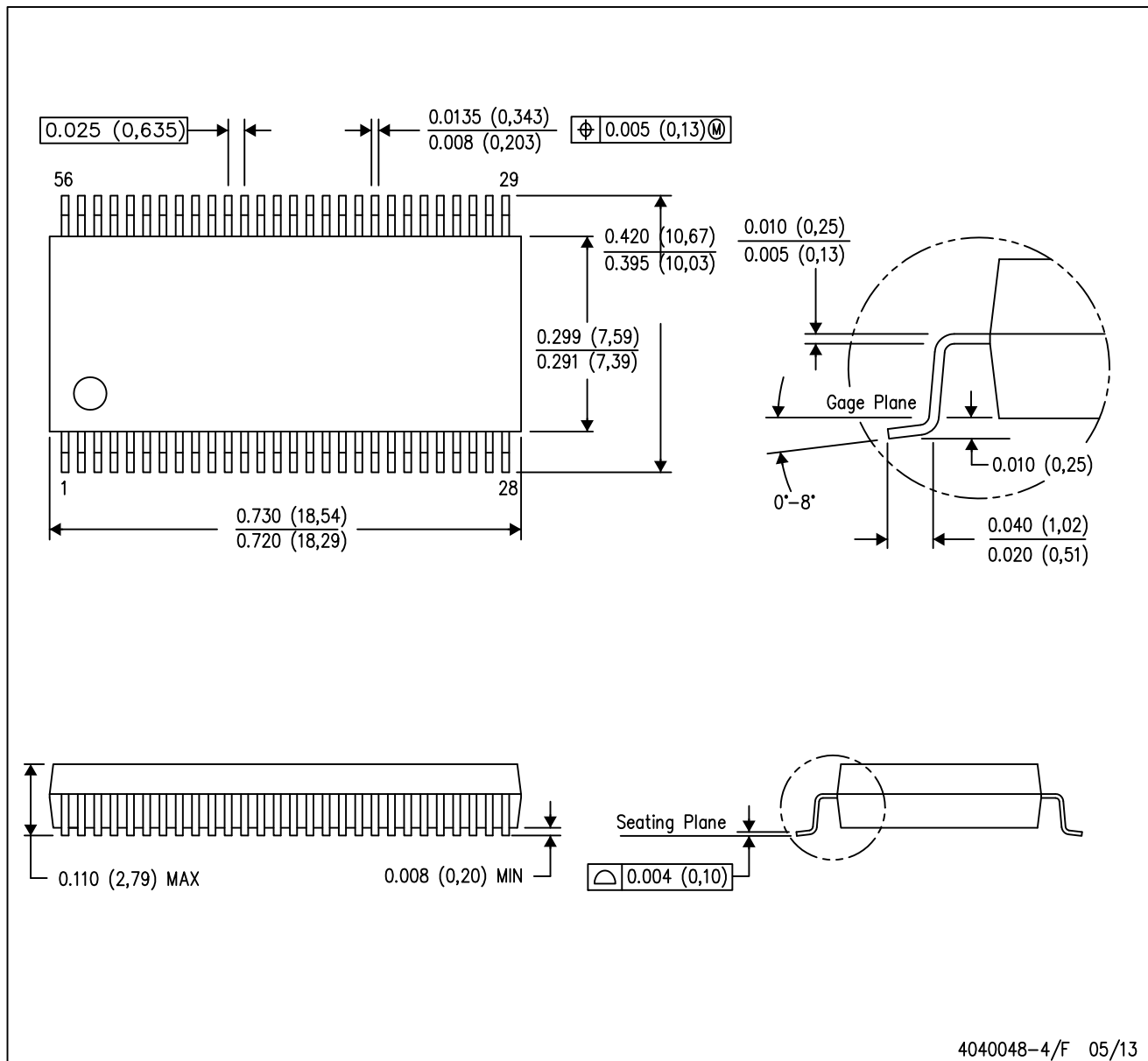

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVT16543DGGR	TSSOP	DGG	56	2000	367.0	367.0	45.0
SN74LVT16543DLR	SSOP	DL	56	1000	367.0	367.0	55.0

MECHANICAL DATA

DL (R-PDSO-G56)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.

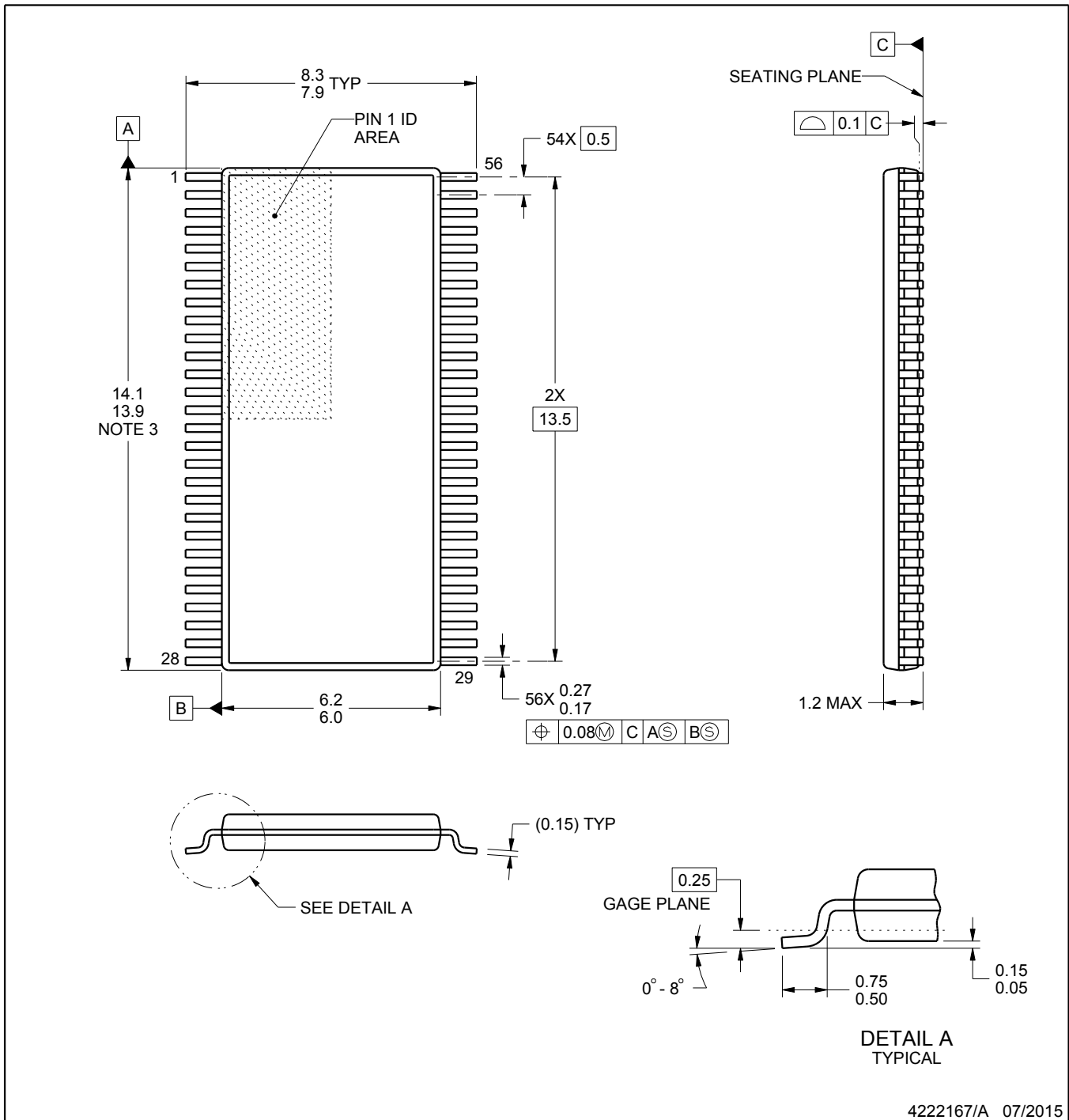
DGG0056A



PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4222167/A 07/2015

NOTES:

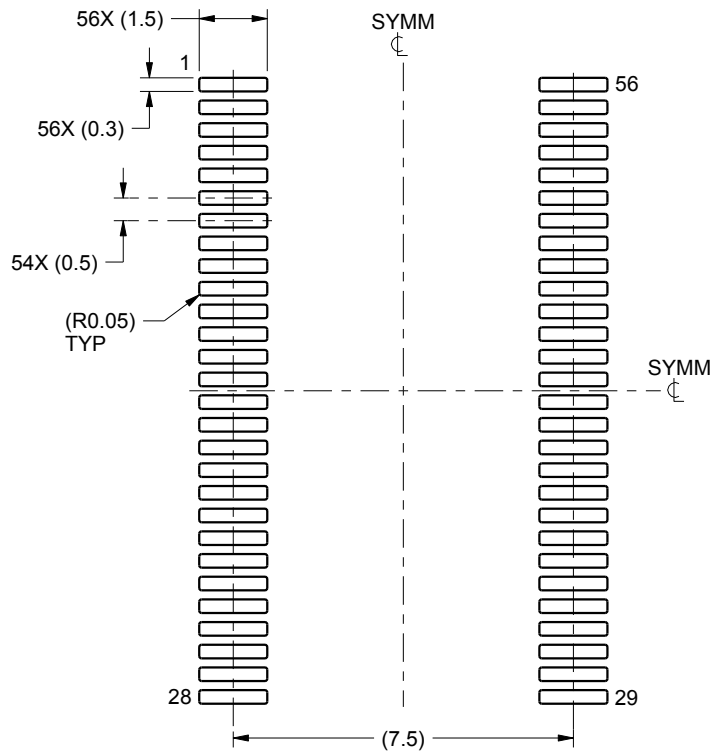
- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
- Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

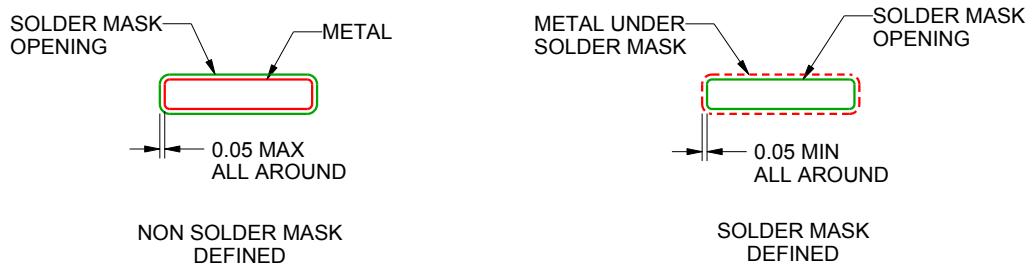
DGG0056A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4222167/A 07/2015

NOTES: (continued)

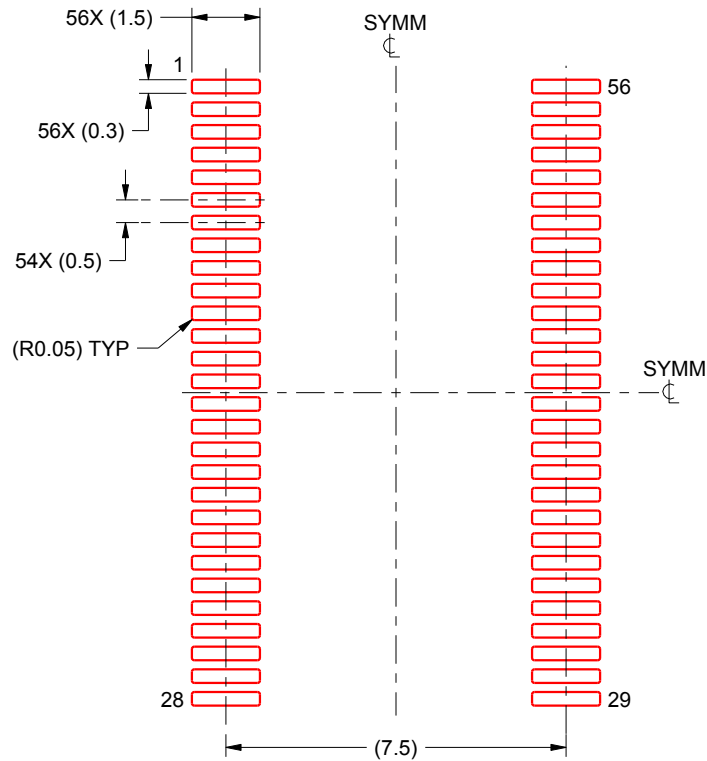
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DGG0056A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4222167/A 07/2015

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com